

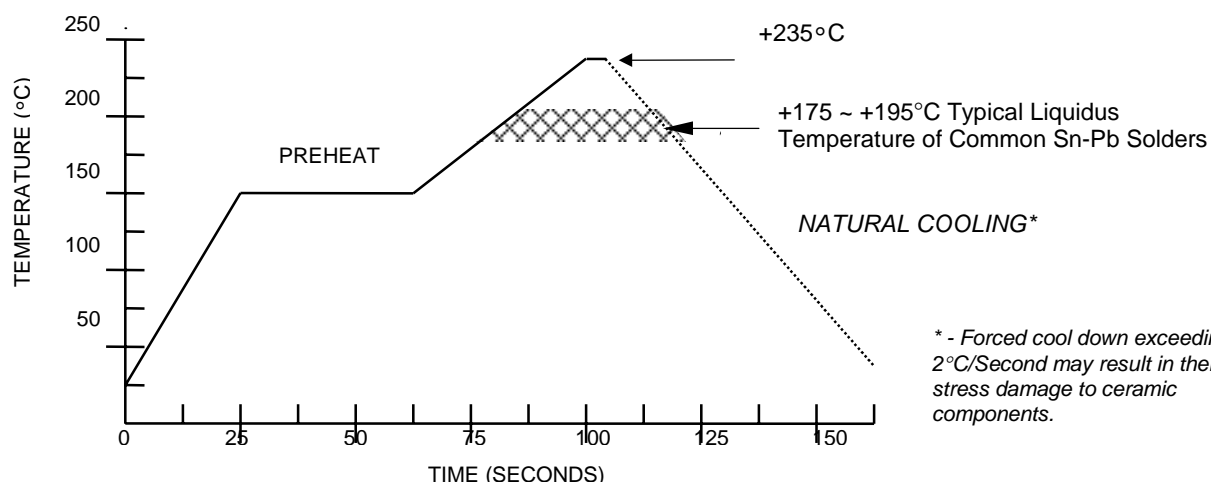


NIC COMPONENTS CORP.

70 Maxess Road • Melville, New York 11747

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RECOMMENDED REFLOW SOLDERING PROFILE (General SMT Products)



TEMPERATURE LIMITS

Peak Temperature	Max. Duration
+260°C	5 SECONDS
+250°C	15 SECONDS
+240°C	25 SECONDS
+230°C	40 SECONDS

The above reflow soldering profile and temperature limits applies to the following NIC surface mount products:

- **NMC** series... Ceramic Chip Capacitors
- **NRC** and **NRSN** series... Thick Film Chip Resistors and Resistor Arrays
- **NTC** series... Tantalum Chip Capacitors
- **NTHC** series... NTC Chip Thermistors
- **NIS** series... 0402/0603 Chip Inductors
- **NCB** series... Ferrite Chip Beads
- **NRD** and **NSD** series... Silicon and Schottky Barrier Rectifier Diodes

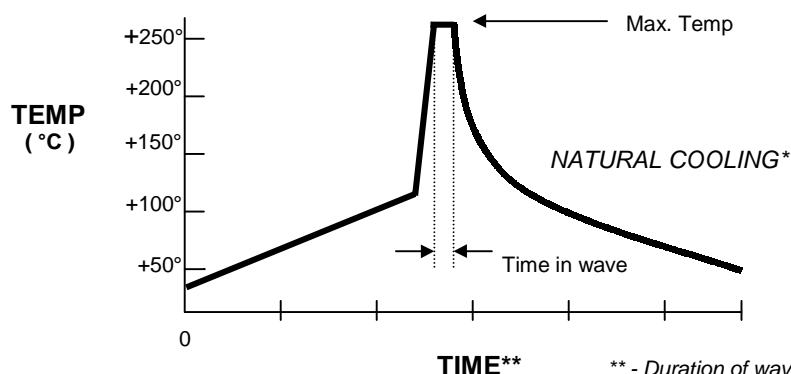


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RECOMMENDED FLOW-WAVE SOLDERING PROFILE (General SMT Products)



* - Forced cool down exceeding 2°C/Second may result in thermal stress damage to ceramic components.

** - Duration of wave soldering cycle is not component dependent. All products identified below can withstand direct immersion in solder without pre-heat. Maximum time within the wave is identified for each component style below.

The above flow-wave soldering profile applies to the following NIC surface mount product series:

Series	Type	Max. Temp.	Max. Time in Wave
NMC	Ceramic Chip Capacitors	+260°C	10 Seconds
NRC NRSN	Thick Film Chip Resistors and Resistor Arrays		
NIS	0402/0603 Chip Inductors		
NTC	Tantalum Chip Capacitors	+260°C	5 Seconds
NIN	Wirewound Chip Inductors		
NCB	Ferrite Chip Beads	+250°C	10 Seconds
NRD NSD	Silicon and Schottky Barrier Rectifier Diodes		
NTHC	NTC Chip Thermistors		
NSFC NSPC	Stacked Film Chip Capacitors	+250°C	5 Seconds